Materials Declaration

Package	MQFP
Body Size	14 X 14
LeadCount	80
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	4.21 E-02	41466
SiO2 Filler	86	4.52 E-01	445756
Phenol Resin	5	2.63 E-02	25916
Antimony_Sb2O3	0.4	2.10 E-03	2073
Brominated Resin	0.4	2.10 E-03	2073
Carbon Black	0.2	1.05 E-03	1037

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	2.94 E-01	289804
Ni	3	9.17 E-03	9038
Si	0.65	1.99 E-03	1958
Mg	0.15	4.58 E-04	452

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	3.00 E-03	2958

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.32 E-02	12979

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.95 E-03	1927

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	1.53 E-01	151038

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	3.04 E-03	2997
Ag Filler	74	8.65 E-03	8529

Molding Compound

Item	PPM	Method
Pb	4.90	EPA method #3052 (ICP-AES)
Cd	<2.0	BS EN 1122:2001B (ICP-AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS In-House Method
PBDE	ND	SGS In-House Method

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

Package Totals

Weight (g)	PPM
1.01 E+00	1000000

STS-S-B

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc any inaccuracy of such information.

ADI Proprietary

08/06/04

Materials Declaration

Package	MQFP
Body Size	14 X 14
LeadCount	80
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	4.21 E-02	41466
SiO2 Filler	86	4.52 E-01	445756
Phenol Resin	5	2.63 E-02	25916
Antimony_Sb2O3	0.4	2.10 E-03	2073
Brominated Resin	0.4	2.10 E-03	2073
Carbon Black	0.2	1.05 E-03	1037

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	2.94 E-01	289804
Ni	3	9.17 E-03	9038
Si	0.65	1.99 E-03	1958
Mg	0.15	4.58 E-04	452

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	3.00 E-03	2958

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.12 E-02	11032
Pb	15	1.97 E-03	1947

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.95 E-03	1927

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	1.53 E-01	151038

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	3.04 E-03	2997
Ag Filler	74	8.65 E-03	8529

Package Totals

Weight (g)	PPM
1.01 E+00	1000000

Molding Compound

Item	PPM	Method
Pb	4.90	EPA method #3052 (ICP-AES)
Cd	<2.0	BS EN 1122:2001B (ICP-AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS In-House Method
PBDE	ND	SGS In-House Method

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

STS-S-A

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